

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Yi-Ling Chan</td><td>05/10/2005</td></tr><tr><td>Fu-Liang Yang</td><td>05/10/2005</td></tr><tr><td>Yi-Ming Sheu</td><td>05/05/2005</td></tr></tbody></table>		Name	Execution Date	Yi-Ling Chan	05/10/2005	Fu-Liang Yang	05/10/2005	Yi-Ming Sheu	05/05/2005				
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<table border="1"><tr><td>Name:</td><td>Taiwan Semiconductor Manufacturing Company, Ltd.</td></tr><tr><td>Street Address:</td><td>No. 8, Li-Hsin Rd. 6</td></tr><tr><td>Internal Address:</td><td>Science-Based Industrial Park</td></tr><tr><td>City:</td><td>Hsin-Chu</td></tr><tr><td>State/Country:</td><td>TAIWAN</td></tr><tr><td>Postal Code:</td><td>300-77</td></tr></table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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CORRESPONDENCE DATA													
Fax Number: (214)200-0853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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NAME OF SUBMITTER:	David M. O'Dell												
Total Attachments: 3 source=assignment#page1.tif source=assignment#page2.tif source=assignment#page3.tif													

CH 10348387 \$40.00

PATENT

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REEL: 016058 FRAME: 0639

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|---------------|----|-----------------------|
| (1) | Yi-Ling CHAN | of | Chu-Nan, Taiwan |
| (2) | Fu-Liang YANG | of | Hsin-Chu City, Taiwan |
| (3) | Yi-Ming Sheu | of | Hsin-Chu, Taiwan |

have invented certain improvements in

Electrostatic Discharge Device Protection Structure

for which we have filed an application for letters patent on January 21, 2003, which has been assigned Application Serial Number 10/348,387; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yi-Ling CHAN

Residence Address: 13F, No. 13, Lane 51, Ming-Chuang St.
Chu-Nan, Miao-Li, Taiwan, R.O.C.

Dated: ✓

Yi-Ling Chan
Inventor Signature

Inventor Name: Fu-Liang YANG

Residence Address: 7F-3, No. 68, University Road
Hsin-Chu, Taiwan, R.O.C.

Dated: ✓ 10th May 2005

Fu-Liang Yang
Inventor Signature

Inventor Name: Yi-Ming SHEU

Residence Address: No. 24, Lane 13b, Jungle Rd.
Hsin-Chu, Taiwan 300, R.O.C.

Dated: ✓

✓
Inventor Signature

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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May-5-2005

✓
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